

East searched
6/3/04 MT

L Number	Hits	Search Text	DB	Time stamp
1	2	6662440.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:43
2	10	("3941636" "4126727" "4648179" "5068714" "5415555" "5669970" "5740730" "5866951" "6118080" "6162856").PN.	USPAT	2004/06/03 13:05
3	10	("3941636" "4126727" "4648179" "5068714" "5415555" "5669970" "5740730" "5866951" "6118080" "6162856").PN.	USPAT	2004/06/03 13:10
4	68	stencil and inner and outer near member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:16
5	7	("2997777" "3923936" "4526098" "4911069" "5181549" "5215724" "5662040").PN.	USPAT	2004/06/03 13:14
6	6	("3877364" "4537658" "4541895" "4911069" "5245932" "5588359").PN.	USPAT	2004/06/03 13:15
7	0	stencil and inner and annular near opening and outer and inner near member and (101/128.21, 101/116 , 101/128.4 , 118/504) .ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:18
8	0	stencil and annular near opening and outer and inner near member and (101/128.21, 101/116 , 101/128.4 , 118/504) .ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:19
9	2	stencil and annular near opening and outer and inner and (101/128.21, 101/116 , 101/128.4 , 118/504) .ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:19
10	2	stencil and annular near opening and (101/128.21, 101/116 , 101/128.4 , 118/504) .ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:19

11	4	stencil and annular near opening and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:38
12	10	("3941636" "4126727" "4648179" "5068714" "5415555" "5669970" "5740730" "5866951" "6118080" "6162856").PN.	USPAT	2004/06/03 13:36
13	1	stencil and annular near opening and (101/127, 101/115 , 118/213 , 118/406 , 228/175 , 228/180.22, 427/282 , 427/96).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:42
14	2	("Re34615" "5522929").PN.	USPAT	2004/06/03 13:41
15	5	stencil and annular near opening and (29/840, 174/253 , 174/255 , 257/737 , 257/738 , 257/E21.514, 29/832 , 29/842 , 29/846).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:48
16	227	Jiang near Tongbi .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:43
17	52	Jiang near Tongbi .inv. and stencil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:48
18	14	("3668028" "4088073" "4269874" "4398462" "4862245" "5240816" "5447757" "5460316" "5478699" "5579583" "5887520" "6016746" "6060117" "6146489").PN.	USPAT	2004/06/03 13:46
19	2	stencil and annular near opening and (438/118, 101/127 , 101/128.21 , 101/128.4 , 438/584).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 13:48

	Title	Current OR
1	Reflective composition of particles with resinous binder and process for preparing same	524/441
2	Z-axis electrical contact for microelectronic devices	174/253
3	Hybrid circuit with an electrically conductive adhesive	257/783
4	Apparatus for depositing solder and adhesive materials onto a printed circuit board	101/127
5	Stencil apparatus for applying solder paste	118/213
6	Electrical interconnection apparatus utilizing raised connecting means	439/74

	Title	Current OR
7	Method of electrically and mechanically connecting a semiconductor to a substrate using an electrically conductive tacky adhesive and the device so made	257/703
8	Process of making interconnection structure for semiconductor device	29/832
9	Resinous polymer sheet materials having selective, decorative effects	428/172

	Title	Current OR
10	Process for forming decorative surface coverings	156/154